

Clean copy of the first full paragraph of page 37, lines 1 to 6:

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As mentioned above, the ceramic heater according to the present invention is thin, light, and practical and is particularly useful for heating and drying semiconductor products in the field of semiconductor industry.

IN THE CLAIMS

Please amend the claims as follows (Clean copies appear below; a marked-up version appears in the Appendix):

Clean copy of claim 1:

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1. (Amended) A ceramic heater comprising:
a disc-shaped ceramic substrate made of nitride ceramic or carbide ceramic,
a heating body formed on a surface of the disc-shaped ceramic substrate, and
a surface opposite the surface having the heating body being a heating surface.

Clean copy of claim 3:

3. (Amended) The ceramic heater according to claim 1,
wherein the heating body comprises a sintered body of metal particles.

B8
(Clean copy of claim 4:)

4. (Amended) The ceramic heater according to claim 1,

wherein the heating body comprises metal particles and metal oxide.

(Clean copy of claim 5:)

5. (Twice Amended) The ceramic heater according to claim 3,

wherein the metal particles are at least one of noble metal, lead, tungsten, molybdenum and nickel.

Clean copy of claim 7:

7. (Twice Amended) The ceramic heater according to claim 1,

wherein the heating body has an aspect ratio at a section of the heating body of about 10 to 10,000.

Clean copy of claim 14:

14. (Amended) A method of producing a ceramic heater according to claim 1, the method comprising:

sintering nitride ceramic powder or carbide ceramic powder to form the substrate made of nitride ceramic or carbide ceramic;

printing an electrically conductive paste on the substrate; and

sintering the electrically conductive paste by heating to form the heating body on the surface of the ceramic substrate.

(Clean copy of claim 15:)

15. (Amended) The method according to claim 14, wherein the electrically conductive paste is a mixed paste of metal particles and metal oxide.

(Clean copy of claim 16:)

16. (Amended) The method according to claim 14, further comprising plating a non-oxidizing metal onto the surface of the resulting heating body.

Please add the following claims 25 to 34:

---25. The ceramic heater according to claim 7, wherein the aspect ratio is about 50 to 5,000.

26. The ceramic heater according to claim 1, wherein the nitride ceramic is at least one metal nitride ceramic comprising aluminum nitride, silicon nitride or titanium nitride and the carbide ceramic is at least one metal carbide ceramic comprising silicon carbide, zirconium carbide, titanium carbide, or tungsten carbide.

27. The ceramic heater according to claim 1, wherein the substrate has a thickness of about 0.5 to 5 mm and the heating body has a thickness of about 1 to 50 μm .

28. The ceramic heater according to claim 27, wherein the heating body has a thickness of about 1 to 10 μm .

29. The ceramic heater according to claim 4,
wherein the metal oxide is at least one of lead oxide, zinc oxide, silicon oxide, boron oxide, aluminum oxide, yttrium oxide and titanium oxide,